Contestant nam	e				
Requirement	Description	Details	Grading	Max points	Given Score
SCH-002	New library			1	
	Name of new library	family_name check terminal name(PDE or SCH) and	_1n/terminal	1	
	U1,U2	numbering,check marking of inverting terminal (any marking is allowed) = 15p		15	
	LCD 1	check terminal name and numbering,check marking of inverting terminal (any marking is allowed) = 5p	-1p/terminal	5	
SCH-003		more or less ICs	-10p/IC		
		more or less discrete components	-5p/comp.		
	Corectness of schematic project	more or less connections (except those caused by more or less components)	-5p/connection	50	
		wrong or missing values	-1p/value		
	Schematic aspect	overlapped symbols/wires/labels, text direction, logic layout, sheet info	-1p/error, but zero for more than 5 errors	8	
PCB-002	Double layer, clearance, width (1+1+1)	check settings if no routing, else check layers, clearance and width using DRC.	-1p/criterion	3	
PCB-003	Vias 0.3/0.7	check settings	zero for any error	2	
	LCD 1, SW1, SW2, SW3, SW4 (3p +3p+3p +3p+3p)	placed on top and fixed position	3p +3p+3p +3p+3p	15	
	all components clearance from holes	placement avoiding 7mm radius(check placement, or settings if placement is	zero for any error	4	
	all components	All TH components on top, SMDs on bottom	zero for any error	4	
PCB-005	footprints according to BOM	check with table 1, BOM	<ul> <li>-1p for each category wrongly associated</li> </ul>	7	
	U1/ LCD/Relay/SW/ Y1/Y2/C+	pads: number, size, spacing (2+2+2)	6p+6p+3p+2p+1p+1p+1p	20	
		keepout, contour	1p+1p+1p+1p+1p+1p+1p	7	
	U2	SOIC-20	1p	1	
	тр	Check size (>0.9mm), clearance (>0.6mm to components, >0.3mm to board edge), status (check if is set as test-point)	-1p for each TP uncomplying with recommendations	2	
PCB-006	24V and return path	track width > 0.55 mm	2p for each net	4	
PCB-007	USBD+ and USBD-	differential (length, simmetry)	5p+4p	9	
PCB-008	USB1USB8	matching length same layer	2p for each net (if all signals are routed)	16	
PCB-009	Solder thief pads U2	2 pads near by pins 10 and 11.	4p for each pad	8	
	U1 orientation	45 deg. Orientation for LQFP	2p if done in PCB	2	
PCB-010	copper clearance, components clearance	min. 1mmSMT, SMB/min. 2mm to board outline.	2p+2p for each criterion	4	
PCB-GEN	Placement into functional blocks	U1, U2, relays, inputs, outputs	5p+5p+5p+5p, -1 for any error	25	

	Symbol-to-footprint correspondence	Check polarized components: capacitors, diodes, MOSFETs connectors, and ICs	2p+2p+2p+2p+2p, zero on each criterion for any error	10	
	Decoupling placement	Check proximity to supply pins (as close as possible)	4p for each capacitor	8	
	Connectors placement	Check edge placement and corresponding block proximity	1p for each connector	6	
	Placement restrictions	Check for components overlapping, placement outside board	-2p for each error	4	
	Routing restrictions	No traces around mounting holes (7mm diameter)	4p, zero on each criterion for any error	4	
	Partial/complete routing		Partial = 1p, complete = 3p.	3	
MEC-001	Board geometry	Length, width(<=dimension)	2p +2p	4	
MEC-002	Shape	Fit panel?	zero for any error	4	
MEC-003	4 holes	Check position, size, nonplating	4p +1p +1p, zero for any error	6	
TST-001	Test grid spacing	Check placement not settings (=2.54 mm)	-1 for any error	8	
TST-003	Global fiducials	Check number (=3), layer(botom) (=copper),position (board corners), size (1.5mm-round), soldermask(>=3), shape=round	1p + 1p + 1p +1p +1p +1p	6	
TST-004	Local fiducials	Check presence, soldermask (any shape/size, center or corner position, same side as component).	1p+1p for U1 and 1p+1p for U2	4	
		Only for complete routing or <= 5 ne	ts unrouted		
FAB-001	Gerber files	TOP, BOT, SMT, SMB, SST, SSB, DRD	1p for each file (7 files)	7	
FAB-002	NPT/PTH holes		4p for two files, zero for any error	4	
FAB-003	PnP file	Check for PnP file, check centered insertion points	1p + 1p	2	
FAB-004	TST file		1p	1	
TOTAL				294	

Evaluation team	Name	Signature
Evaluator 1		
Evaluator 2		
Student	I agree with the evaluation of my subject and I accept my final score!	